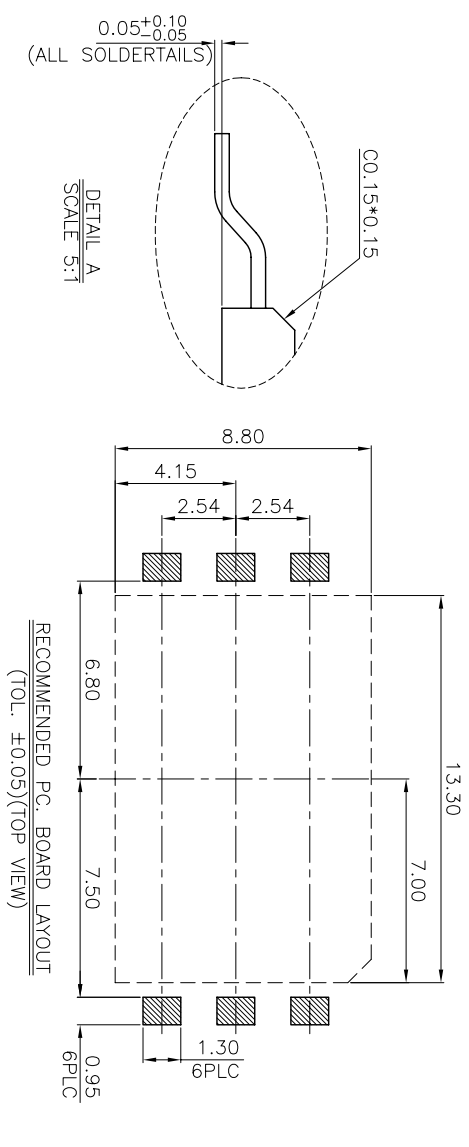
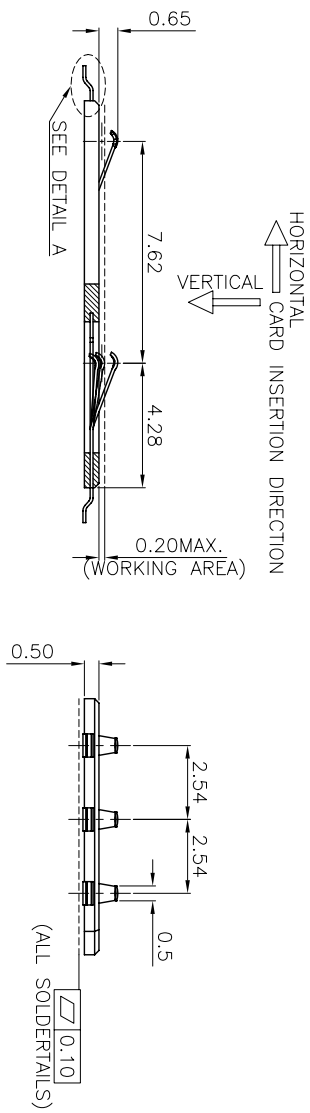
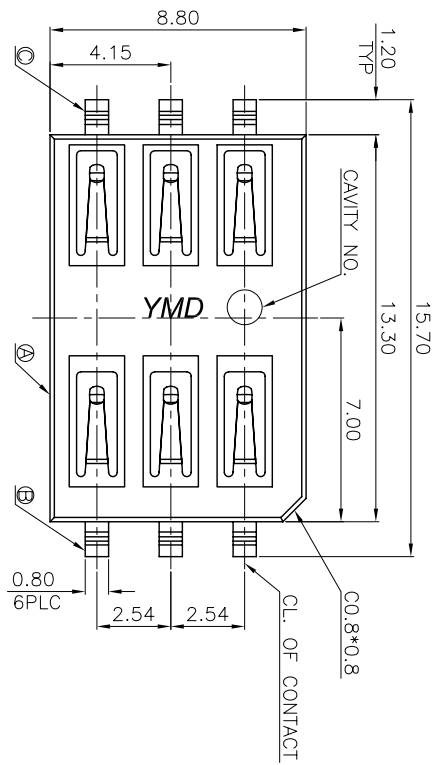
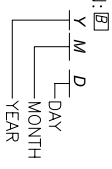
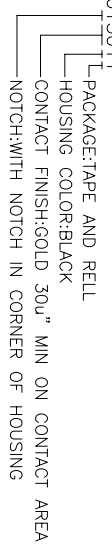


REV.	ECN NO OR DESCRIPTION	REVISED	DATE
A	PRODUCT RELEASE	ZK.CHEN	03/09/07
B	ECN-0070107-2/3 CHANGE D/C	Charlie Gul	05/22/07



- NOTE:
- MATERIAL:  
HOUSING:HIGH THERMAL PLASTIC.W/30% GF.UJ94V-0,COLOR BLACK.  
CONTACT A&CONTACT B:COPPER ALLOY,T=0.10;
  - FINISH:  
CONTACT A&CONTACT B:  
30u" MIN GOLD PLATING ON CONTACT AREA;  
1u" MIN GOLD PLATING ON SOLDER TAILS;  
50u" MIN NICKEL UNDERPLATING OVERALL.
  - SPECIFICATION:SEE 2.54mm PITCH SIM CARD SMT TYPE PRODUCT SPEC.
  - SOLDER HEAT RESISTANCE: REFLOW SOLDERING 260° FOR 10SEC.
  - TO CONFORM TO THE "SE-01-001" & "ROHS DIRECTIVE";
  - GREEN PRODUCT IDENTIFICATION IN PACKING:**[G.P. PASS]**
  - FOR REFLOW SOLDERING LEED FREE PROCESS.
  - P/N DESCRIPTION:  
2SM2000-013011



C	CONTACT B	3	COPPER ALLOY 0.10T	SEE NOTES
B	CONTACT A	3	COPPER ALLOY 0.10T	SEE NOTES
A	HOUSING	1	HI-THERMAL PLASTIC.UJ94V-0	COLOR:BLACK
NO	DESCRIPTION	QTY	MATERIAL	PLATING&COLOR

UNLESS OTHERWISE SPECIFIED TOLERANCES

DECIMALS:	ANGLES:	TITLE	2.54mm PITCH SIM CARD 6P 0.5H SMT TYPE
X : ±0.5	X : ±2°	DMW	2SM2000-013011
XX : ±0.3	XX : ±1°	CHKD	SCALE: N/A
XXX : ±0.2		APVD	UNIT: mm

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